

## Ball-Wedge Bonder 5610

### Bond System

<b>Wire types</b>	Gold wire 17,5-50µm on 2" spool
<b>Bondhead</b>	Ball-Wedge for gold wire Standard capillaries 16mm length, (opt. 19 mm)
<b>Ultrasonic System</b>	F&S Generator 68 kHz (optional 120, 140kHz)

### Bonder Base

#### Axes

- Working area X/Y-axis 100x100mm  
Z-axis 60mm
- Step resolution 0,25µm
- Repeatability <2µm

#### Hardware

- Dual Core PC, 1,6 GHz processor,
- 4 GB RAM, Ethernet, 4x USB-Hub Front
- Firewire CCD colour camera 1,4 MPixel
- Network-capable with TCP / IP server

#### Software

- Single bonds up to complex programs,
- Loop shapes can be saved in libraries
- Optional pattern recognition

**Placement accuracy:** +/- 5µm @ 3 sigma, incl. Tool / no wire  
on F&S Bondtec standard substrate

**Repeatability:** +/- 3 µm @ 3 sigma, incl. Tool / without wire  
on F&S Bondtec standard substrate

**Loop height accuracy:** +/- 5µm @ 3 sigma, for thin wire 5630  
with 25µm aluminum wire on F&S Bondtec  
standard substrate

### Die 56xx Series:

The semi-automatic Gold Ball-Bonder 5610 fills the gap between the manual and semi-automatic Ball Bonder.

The 5610 is fully PC controlled and allows any number of bonds and bumps to be programmed. Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds or bumps are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual/automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

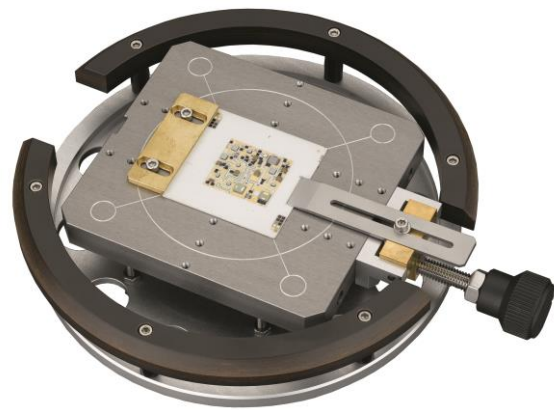
The 5610 can also be used as Thin Wire Wedge Wedge or Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

Set-up time: ~ 3 minutes.  
Ask us for more information!

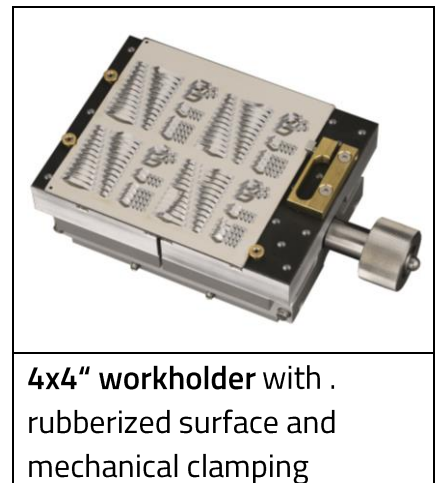
- Speed** 20 wires per minute
- Dimensions** W x D x H – 70 x 65x 70 cm, weight approx. 80kg
- Connections** 100-240 VAC, 1 Phase, 50/60 Hz, max 500 VA  
Ø 6mm standard vacuum tubing
- Heater controller** integrated in the machine 0-250C°

## Workholder

Standard-Workholder  
for parts up to 4x4"  
with Vacuum und mechanical clamping



## Optional:



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